



## Material Content Data Sheet



<b>Sales Product Name</b>		SPA04N50C3		<b>Issued</b>		29. August 2013			
<b>MA#</b>		MA000358762							
<b>Package</b>		PG-TO220-3-31		<b>Weight*</b>		2258.08 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.265	0.14	0.14	1446	1446	
leadframe	non noble metal	zinc	7440-66-6	0.925	0.04		410		
	non noble metal	copper	7440-50-8	615.788	27.27	27.31	272704	273114	
wire	non noble metal	aluminium	7429-90-5	0.982	0.04	0.04	435	435	
encapsulation	organic material	carbon black	1333-86-4	2.262	0.10		1002		
	plastics	epoxy resin	-	212.649	9.42		94172		
	inorganic material	silicondioxide	60676-86-0	916.200	40.59	50.11	405744	500918	
leadfinish	non noble metal	tin	7440-31-5	6.173	0.27	0.27	2734	2734	
plating	non noble metal	nickel	7440-02-0	0.671	0.03	0.03	297	297	
solder	non noble metal	antimony	7440-36-0	0.208	0.01		92		
	noble metal	silver	7440-22-4	0.521	0.02		231		
	non noble metal	tin	7440-31-5	1.353	0.06	0.09	599	922	
heatspreader	non noble metal	zinc	7440-66-6	0.746	0.03		330		
	non noble metal	copper	7440-50-8	496.335	21.98	22.01	219804	220134	
*deviation	< 10%					Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com